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## NOTE

- 1. RATING : 50mA, DC12V Max
- 2. CIRCUIT : 1C 1P.
- 3. OPERATING FORCE : 250±50gf
- 4. CONTACT RESISTANCE :  $100m\Omega$  Max
- 5. TRAVEL : 0.7±0.15m/m
- 6. SOLDER THICKNESS : 0.15±0.03mm
- 7. PACKAGE : 3,000PCS

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PA	RT N	10	PART NA	ME	Q'TY	МАТ	ERIAL	STAND	ARD	DISPOSITION	REMARKS
				Т О	RIGON- METRY	ÚNIT	SCALE 10	1 5	SMD	TACT SW	ITCH
A				A	APPD	CHKD	DSGD				
A											
A								MODEL			ED
NO		•	CORRECTION							NI-143002	JD

# INNOCENT ELECTRONICS CO.

#### P.C.B DIMENSION

1. GENE	ERAL SPECIFICATION										
1.1 SWIT	CH ACTION	: PUSH-ON TYPE S.P.S.T									
1.2 SWIT	CH RATING	: DC12V 50mA									
1.3 OPF	RATION TEMPERATURE RANG	-20.22 + 30.177									
1.4 PRFS	1.4 PRESERVATIVE TEMPERATURE RANGE SINGLE CONDITION $\cdot -40 \sim +85^{\circ}$										
TAPIG CONDITION : -20~+60 °C											
1.5 APPF	1.5 APPEARANCE AND DIMENSIONS : SEE OUTSIDE DRAWING PAGE										
1.6 STAN	1.6 STANDARD CONDITIONS UNLESS OTHERWISE SPECIFIED. THE TEST AND MEASUREMENTS SHALL BE CARRIED										
OUT	OUT AS FOLLOWS :										
	AMBIENT TEMPERATURE	: 5~35℃	: 5~35°C								
	RELATIVE HUMIDITY	: 45~85%									
	AIR PRESSURE	: 86~106kPa									
HOW	ever, if doubt arises on	THE DECISION BASED ON THE MEAS	SURED VALU	ES UNDER TH	IE ABOVE- <i>N</i>	IENTIONED					
CON	DITIONS, THE FOLLOWING C	CONDITIONS SHALL BE EMPLOYED									
	AMBIENT TEMPERATURE	:20±2℃									
	RELATIVE HUMIDITY	:65±5%									
	AIR PRESSURE	: 86~105kPa									
2. PERFO	RMANCE										
2.1 ELEC											
NO	ITEM	TEST CONDI	TION		PERFO	RMANCE					
2.1.1	CONTACT	PUSH FORCE : (OPERATION F	$ORCE) \times 2$		100mΩ MA	۸X.					
	RESISTANCE	1kHz, 20mV, 5~50mA									
		MEASUREMENT TOOL : CONTAC	t resistanc	E METER							
		(1kHz, 20mV,									
2.1.2	INSULATION	DC100V(BETWEEN TERMINALS)	DC100V(BETWEEN TERMINALS)								
	RESISTANCE										
2.1.3	WITHSTAND	A.C.250V FOR 1 MINUTE. (BETWEEN TERMINALS)			NO INSULATION						
	VOLTAGE				DESTRUCTION						
2.1.4	BOUNCING	OPERATION SPEED : 3~4 TIMES/S			BOTH ON						
					10ms M	AX.					
					BOTH OFF						
		$T = 10k\Omega \leq$	$\leq \int_{\alpha}$								
		1mA									
	SWITCH BOUNCING TEST CIRCUIT										
L	I				1						
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S/W TYPE	SMD TACT SWIT	СН				. /					
MODEL NO	D. INT-1430										
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2.2 M	ECHANICAL CHARACT	ERISTICS					
NO.	ITEM	TEST CONE	DITION		PERFOR	MANCE	
2.2.1	OPERATION FORCE	PUSH BY RECOMMEN OPERATING	CONDITION.( PUSH FORC RETURN FO EL TO CLOSURE	(4.2) CE IRCE -	PUSH FORCE 160 OR 250 RETURN FORC 10gf MIN.	9±50gf CE	
2.2.2	TRAVEL TO CLOSURE	F=(OPERATION FORCE)×2	F <b>V</b>	TRAVEL	0.7±0.15m	m	
2.2.3	PUSH STRENGTH	50N FOR 60 SEC.	<b>F</b> 90°		NO DAMAGE (ELECTRICAL MECHANICA	and L)	
2.2.4	PULL STRENGTH	VERTICAL DIRECTION	$\rightarrow$	HORIZONTAL DIRECTION	VERTICAL DIR 50gf MIN. HORIZONTAL 50gf MIN.	ECTION : DIRECTION :	
2.2.5	VIBRATION TEST	<ol> <li>AMPLITUDE : 1.5mm</li> <li>SWEEP RATE : 10-55-10Hz FOR 1 MINUTE</li> <li>VIBRATION DIRECTION : X, Y, Z(3 DIRECTIONS)</li> <li>TIME : EACH DIRECTION 2 HOURS(TOTAL 6 HOURS)</li> </ol>			NO. 2. 1 AND 2.2.1 TO 2.2.2 SATISFIED	SHALL BE	
2.2.6	SOLDERING HEAT TEST	MOUNT THE SWITCH ON P.W.B BY ADHESIVE 1) REFLOW PRESS 2 TIMES.(REFER TO SECTION 3.1) 2) STANDARD CONDITIONS AFTER TEST : 24 HOURS			CONTACT RESISTANCE 100mΩ MAX. NO. 2.1.2 TO 2.1.4 AND NO. 2.2.1 TO 2.2.2 SHALL BE SATISFIED.		
2.2.7	SOLDERBILITY	TEMPERATURE : 230±5℃ SOLDERING TIME : 2±0.5 SEC.	70% OR MORE OF SURFACE AREA OF THE PORTION IMMERSED IN SOLDER SHALL BE COVERED BY NEW SOLDEI				
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<u>.</u>	ITEM	TEST CONDI			PERFO	RMANCE		
.3.1	COLD TEST	<ol> <li>1) TEMPERATURE : -40±2°C</li> <li>2) DURATION OF TEST : 500 h</li> <li>3) TAKE OFF A DROP WATER.</li> <li>4) STANDARD CONDITIONS AFTER TE</li> </ol>	CONTACT RESISTANCE 200mΩ MAX. NO., 2.1.2 TO 2.1.4 AND NO. 2.2.1 TO 2.2.2 SHALL					
2.3.2	HEAT TEST	1) TEMPERATURE : 85±2°C 2) DURATION OF TEST : 500 h 3) STANDARD CONDITIONS AFTER TE	CONTACT RESISTANCE 200mΩ MAX. NO., 2.1.2 TO 2.1.4 AND NO. 2.2.1 TO 2.2.2 SHALL BE SATISFIED.					
.3.3	TEMPERATURE CYCLE	1) TEST CYCLE : 20 CYCLES 2) STANDARD CONDITIONS AFTER TE TEMPERATURE DURATION OF 1 20 $\pm$ 5°C 2~3 MINUT C -40 $\pm$ 2°C 1 h C 20 $\pm$ 5°C 2~3 MINUT E 85 $\pm$ 5°C 1 h	ST : 1 h TEST E E		CONTACT RE 200mΩ MAX. NO., 2.1.2 TO NO. 2.2.1 TO BE SATISFIED.	SISTANCE 2.1.4 AND 2.2.2 SHALL		
.3.4	HUMIDITY TEST	<ol> <li>1) TEMPERATURE : 60±2°C</li> <li>2) RELATIVE HUMIDITY : 90~95%</li> <li>3) DURATION OF TEST : 500 h</li> <li>4) TAKE OFF A DROP WATER.</li> <li>5) STANDARD CONDITIONS AFTER TE</li> </ol>	CONTACT RESISTANCE 200mΩ MAX. NO., 2.1.2 TO 2.1.4 AND NO. 2.2.1 TO 2.2.2 SHALL BE SATISFIED.					
2.3.5	ENDURANCE (SWITCHING ACTION)	ICE 1) D.C 15V 20mA RESISTANCE LOAD NG 2) OPERATION SPEED : 2~3 TIMES/S 3) PUSH FORCE : MAXIMUM VALUE OF OPERATION FORCE 4) OPERATION NUMBER : 1,000,000 TIMES				CONTACT RESISTANCE 20Q MAX. BOUNCING : 10 ms MAX. VARIATION RATE OF OPERATION FORCE SHALL BE WITHIN ±30% TO THE VALUE BEFORE TESTING NO. 2.1.2 AND 2.2.2 SHALL BE SATISFIED.		
2.3.6	WITHSTAND H2S	ITHSTAND H2S 1) DENSITY : 3±1 ppm 2) TEMPERATURE : 40±2°C 3) RELATIVE HUMIDITY : 80% 4) DURATION OF TEST : 24 h 5) STANDARD CONDITIONS AFTER TEST : 1 h				CONTACT RESISTANCE 200mΩ MAX. NO., 2.1.2 TO 2.1.4 AND NO. 2.2.1 TO 2.2.2 SHALL BE SATISFIED.		
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# 3. PRECAUTION

3.1 REFLOW SOLDERING CONDITION



1) RE-SOLDERING BY SOLDERING IRON SHALL BE ALLOWED UNDER 280°C MAX. 3 SEC. MAX. 1 TIME. SOLDERING IRON FOR RE-SOLDERING HAVE TO 20W MAX.

## 3.2 DESIGN INSTRUCTIONS

- 1) FOLLOW RECOMMENDED P.W.B PIERCING PLAN IN OUTSIDE DRAWING PAGE.
- 2) DESIGN KEY TOP AS FIG-1. DESIGN INCLINATION OF KEY TOP 4 DEG. MAX. AS FIG-2. TOLERANCE BETWEEN SWITCH AND KEY TOP IS WITHIN 0.3mm

(RECOMMENDED OPERATING CONDITION)





FIG

3.3 NOTES

1) PLEASE BE CAUTIONS NOT TO GIVE EXCESSIVE STATIC LOAD OR SHOCK TO SWITCHES.

- 2) PLEASE BE CAREFUL NOT TO PILE UP P.W.B AFTER SWITCHES WERE SOLDERED.
- 3) PRESERVATION UNDER HIGH TEMPERATURE AND HIGH HUMIDITY OR CORROSIVE GAS SHOULD BE AVOIDED ESPESIALLY. WHEN YOU NEED TO PRESERVE FOR A LONG PERIOD, DO NOT OPEN THE CARTON.
- 4) DO NOT PUSH THE PLASTIC FILM WITH SHARP EDGE POLE.
- IT WILL CAUCE A FAILURE OF SEALING.
- 5) CLEANING

\*IT FLUX OR SOLDER IS SCATTERED ON THE SURFACE OR CONTACT PORTION WHEN SOLDERING, CHARACTERISTICS OF THIS PRODUCT MAY BE DAMAGED.

\*CLEANING AFTER SOLDERING IS NOT ALLOWED. WHEN CLEANING IS REQULRED NECESSARILY, AFTER-FITTED SHOULD BE CONDUCTED.

6) AVOID THE USE OF THE SWITCH UNDER PUSHED ON CONDITION IS CONTINUED FOR A LONG TIME.

7) THERE IS A POSSIBILITY THE FLUX FROM SOLDER PASTE INFILTRATES INTO THE BODY IF PLENTY OF SOLDER PASTE WAS APPLIED BY SWITCH ON THE P.C.B.

SO WE RECOMMEND TO USE OUR PROPOSED LAND DESIGN IN ORDER TO PREVENT ABOVE PROBLEM. ALSO PLEASE AVOID PUTTING ADDITIONAL LAND BY THE SWITCH ON THE P.C. B.

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